

50V PRE-BIASED SMALL SIGNAL SURFACE MOUNT PNP TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

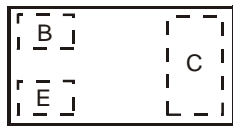
Mechanical Data

- Case: DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0009 grams (approximate)

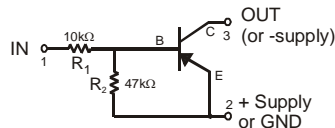
DFN1006-3



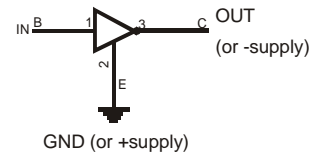
Bottom View



Top View
Pin-Out



Device Symbol



Equivalent Inverter
Circuit

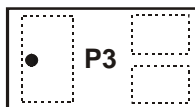
Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTA114YLP-7	P3	7	8	3,000
DDTA114YLP-7B	P3	7	8	10,000

- Notes:
1. No purposefully added lead.
 2. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>.
 3. For packaging details, go to our website at <http://www.diodes.com>.

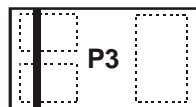
Marking Information

DDTC113TLP-7



Top View
Dot Denotes
Collector Side

DDTC113TLP-7B



Top View
Bar Denotes Base
and Emitter Side

P3 = Product Type Marking Code

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	-50	V
Input Voltage	V _{IN}	+6 to -40	V
Output Current	I _O	-70	mA
Output (Collector) Current	I _{C(MAX)}	-100	mA

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P _D	250	mW
Power Derating above 25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 4) (Equivalent to one heated junction of PNP)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics: Discrete PNP Transistor (Q1) @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Off Characteristics (Note 5)						
Collector-Base Breakdown Voltage	BV _{CBO}	-50	—	—	V	I _C = -10μA, I _E = 0
Collector-Emitter Breakdown Voltage	BV _{CEO}	-50	—	—	V	I _C = -1.0mA, I _B = 0
Collector-Base Cut Off Current	I _{CBO}	—	—	-0.1	μA	V _{CB} = -50V, I _E = 0
Collector-Emitter Cut Off Current, I _{O(off)}	I _{CEO}	—	—	-0.5	μA	V _{CB} = -50V, I _B = 0
Emitter-Base Cut Off Current	I _{EBO}	—	—	-0.2	mA	V _{EB} = 4V, I _C = 0
Input Off Voltage	V _{I(off)}	—	—	-0.3	V	V _{CC} = -5V, I _O = -100uA
On Characteristics (Note 5)						
Input-On Voltage	V _{I(on)}	-1.4	—	—	V	V _O = -0.3V, I _O = I _C = 1mA
Input Current	I _I	—	—	-0.88	mA	V _I = -5V
DC Current Gain	h _{FE}	80	—	—	—	V _{CE} = -5V, I _C = -5mA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	—	-0.25	V	I _C = -50mA, I _B = -2.5mA
Output On Voltage	V _{O(on)}	—	-0.1	-0.3	V	I _I = -0.25mA, I _O = -5mA
Input Resistance	R ₁	7	10	13	KΩ	—
Resistance Ratio	(R ₂ /R ₁)	3.7	4.7	5.7	—	—
Small Signal Characteristics						
Current Gain-Bandwidth Product	f _T	—	250	—	MHz	V _{CE} = -10V, I _E = -5mA, f = 100 MHz

- Notes:
- Device mounted on FR-4 PCB, 1" x 0.85" x 0.062".
 - Short duration pulse test used to minimize self-heating effect. Pulse width t_p < 300μs, Duty Cycle, d ≤ 2%.

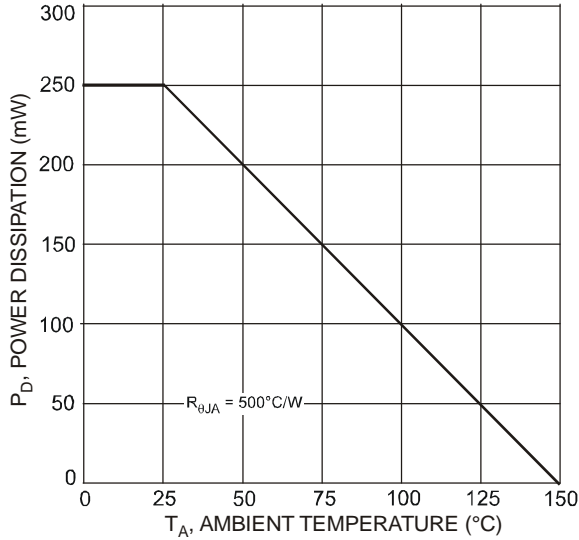


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 4)

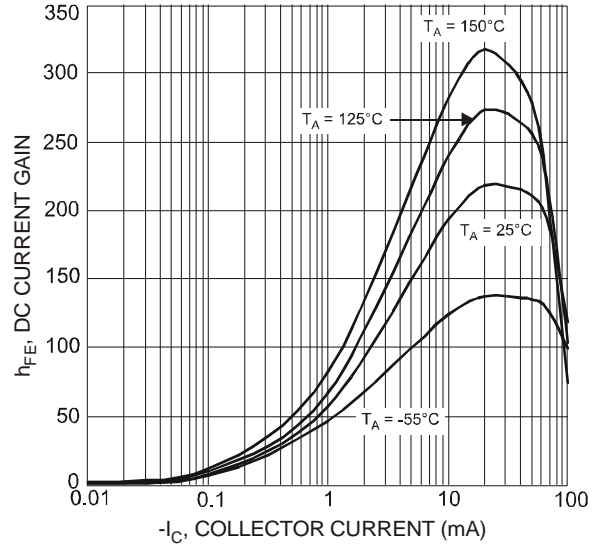


Fig. 2 Typical DC Current Gain vs. Collector Current

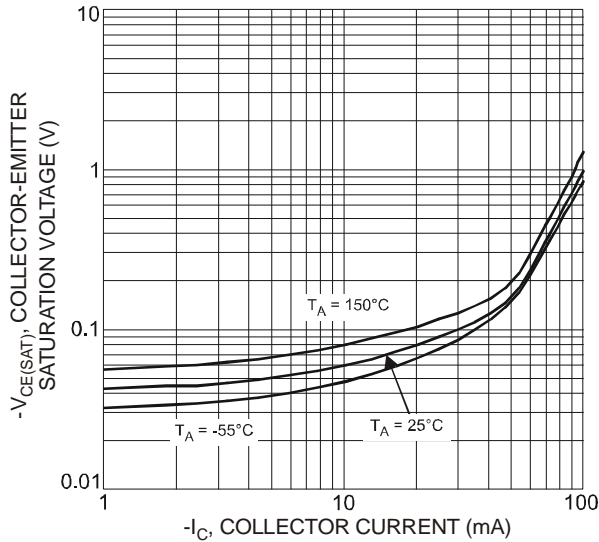


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

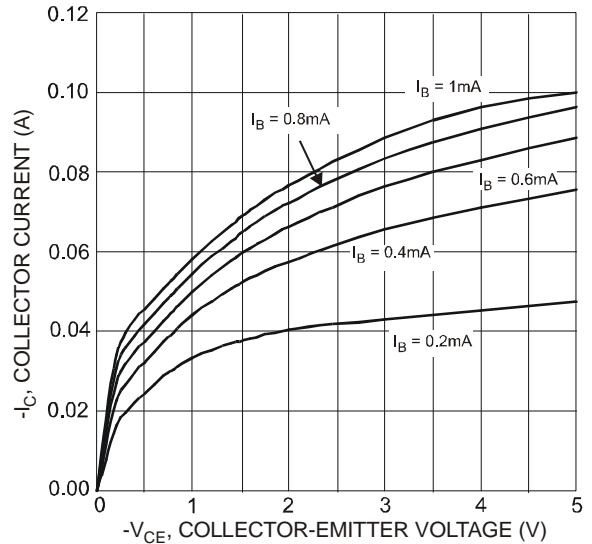


Fig. 4 Typical Collector Current vs. Collector-Emitter Voltage

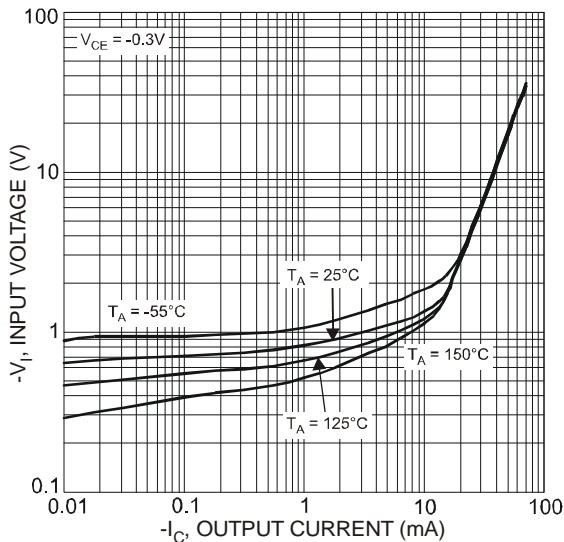


Fig. 5 Typical Input Voltage vs. Output Current (On Characteristics)

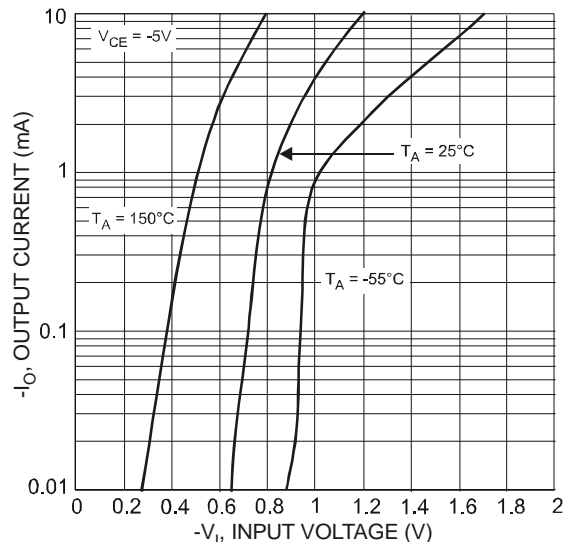
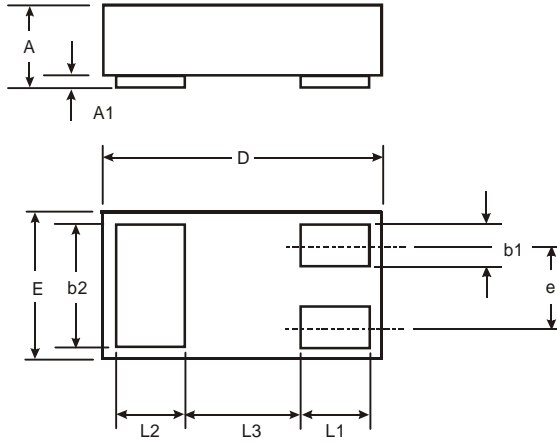


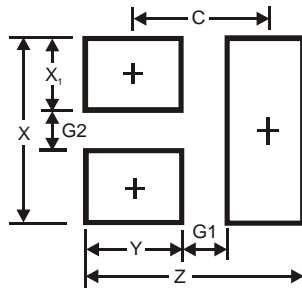
Fig. 6 Typical Output Current vs. Input Voltage (Off Characteristics)

Package Outline Dimensions



DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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